PROCESS FOR INTEGRATED CIRCUIT WIRING

ABSTRACT

Metal wiring is provided in an integrated circuit by sputter coating onto a semiconductor substrate a copper seed (2) layer; depositing and patterning a photoresist; electroplating or electrolessly plating a metal within the openings of the photoresist (3); stripping the remaining photroresist (3) and etching the copper seed layer with an etchant that preferentially etches the copper seed layer at a rate higher than that for the electroplated or electrolessly plated metal.

Fig 4